This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (previously amended): A piezoelectric oscillator unit comprising:

a circuit substrate including a cavity provided therein and a wall provided around the cavity, the wall having a top surface with electrodes disposed thereon, the circuit substrate having an oscillatory circuit mounted in the cavity thereof;

C1

a vibrator package overlaid on said circuit substrate, said vibrator package housing a piezoelectric member therein and said vibrator package having electrodes provided on the bottom surface thereof which are bonded to said electrodes provided on the top surface of the wall of said circuit substrate; and

an adhesive arranged between the top surface of said wall of the circuit substrate and the bottom surface of said vibrator package to bond said circuit substrate and said vibrator package together.

Claim 2 (original): A piezoelectric oscillator unit according to Claim 1, wherein said adhesive is a thermosetting adhesive.

Claim 3 (original): A piezoelectric oscillator unit according to Claim 1, wherein said adhesive is solder.

Claim 4 (previously amended): A piezoelectric oscillator unit according to Claim 1, wherein the circuit substrate is defined by a multilayer ceramic substrate, and the cavity is disposed at the approximate center thereof to mount components.

Claim 5 (canceled)

Claim 6 (previously amended): A piezoelectric oscillator unit according to Claim 1, wherein said electrodes on the top surface of the wall are provided at four corners of

the top surface of the wall, and external electrodes are provided at four corners of the bottom surface of the wall.

Claim 7 (original): A piezoelectric oscillator unit according to Claim 4, wherein a transistor for oscillation and buffer amplification, a varicap diode, a multilayer capacitor, a chip thermistor for temperature compensation, and a chip resistor are surface-mounted within said cavity.

C1

Claim 8 (original): A piezoelectric oscillator unit according to Claim 1, further comprising a case arranged to receive said vibrator package, and a shielding plate arranged on said case to hermetically seal said vibrator package.

Claim 9 (original): A piezoelectric oscillator unit according to Claim 1, wherein said circuit substrate includes via holes arranged to connect said electrodes provided on the bottom surface of said circuit substrate to said electrodes provided on said top surface of said circuit substrate.

Claim 10 (previously amended): A piezoelectric oscillator unit comprising:

a circuit substrate having an oscillatory circuit mounted thereon;

a vibrator package overlaid on said circuit substrate, said vibrator package having a top surface and a bottom surface and housing a piezoelectric member therein and said vibrator package having electrodes provided on the bottom surface thereof which are bonded to electrodes provided on the top surface of said circuit substrate;

a shielding case covering said vibrator package so that said shielding case contains said vibrator package; and

an adhesive arranged between the top surface of said vibrator package and said shielding case to adhere said shielding case to said vibrator package

Claim 11 (previously amended): A piezoelectric oscillator unit comprising:

a circuit substrate having an oscillatory circuit mounted thereon;

a vibrator package overlaid on said circuit substrate, said vibrator package housing a piezoelectric member therein and said vibrator package having electrodes provided on the bottom surface thereof which are bonded to electrodes provided on the top surface of said circuit substrate;

C1

a shielding case covering said vibrator package so that said shielding case contains said vibrator package; and

an adhesive arranged to adhere said shielding case to said circuit substrate;

wherein said shielding case is provided with protrusions, said circuit substrate is provided with holes, each of said protrusions is inserted into a corresponding one of said holes, and said protrusions are fixed in said holes by said adhesive which is filled in said holes.

Claim 12 (original): A piezoelectric oscillator unit according to Claim 10, wherein said adhesive is a thermosetting adhesive.

Claim 13 (original): A piezoelectric oscillator unit according to Claim 11, wherein said adhesive is a thermosetting adhesive.

Claim 14 (original): A piezoelectric oscillator unit according to Claim 10, wherein said adhesive is solder.

Claim 15 (original): A piezoelectric oscillator unit according to Claim 10, wherein said vibrator package is a quartz vibrator package.

Claim 16 (original): A piezoelectric oscillator unit according to Claim 11, wherein said protrusions of said shielding case are claws.

Canceld C1

Claim 17 (original): A piezoelectric oscillator unit according to Claim 10, wherein the circuit substrate is defined by a multilayer ceramic substrate, and includes a cavity disposed at the approximate center thereof to mount components.

Claim 18 (original): A piezoelectric oscillator unit according to Claim 17, wherein said multilayer ceramic substrate includes a wall provided around the cavity.

Claim 19 (previously amended): A piezoelectric oscillator unit comprising:

a circuit substrate having an oscillatory circuit mounted thereon;

a vibrator package overlaid on said circuit substrate, said vibrator package housing a piezoelectric member therein and said vibrator package having electrodes provided on the bottom surface thereof which are bonded to electrodes provided on the top surface of said circuit substrate;

a shielding case covering said vibrator package so that said shielding case contains said vibrator package; and

an adhesive arranged to adhere said shielding case to said circuit substrate;

wherein the circuit substrate is defined by a multilayer ceramic substrate, and includes a cavity disposed at the approximate center thereof to mount components;

said multilayer ceramic substrate includes a wall provided around the cavity; and

said electrodes are provided at four corners of the top surface of the wall, and external electrodes are provided at four corners of the bottom surface of the wall.